

RCX700N20

Nch 200V 70A Power MOSFET

V_{DSS}	200V
R _{DS(on)} (Max.)	42.7m $Ω$
I _D	70A
P_D	83W

Features

- 1) Low on-resistance.
- 2) Fast switching speed.
- 3) Drive circuits can be simple.
- 4) Parallel use is easy.
- 5) Pb-free lead plating; RoHS compliant
- 6) 100% Avalanche tested

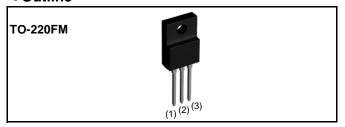
Application

Switching Power Supply

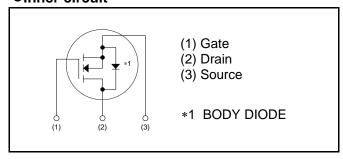
Automotive Motor Drive

Automotive Solenoid Drive

Outline



•Inner circuit



Packaging specifications

	Packaging	Bulk
Re	Reel size (mm)	-
Tyroo	Tape width (mm)	-
Type	Quantity (pcs)	500
	Taping code	-
	Marking	RCX700N20

● Absolute maximum ratings (T_a = 25°C)

Paramete	Symbol	Value	Unit	
Drain - Source voltage	V _{DSS}	200	V	
Continuous drain surrent	T _c = 25°C	I _D *1	±70	А
Continuous drain current	T _c = 100°C	I _D *1	±38	А
Pulsed drain current	I _{D,pulse} *2	±140	А	
Gate - Source voltage	V _{GSS}	±30	V	
Avalanche energy, single pulse	E _{AS} *3	396	mJ	
Avalanche current	I _{AR} *3	35	А	
$T_c = 25^{\circ}C$		P _D	83	W
Power dissipation $T_a = 25^{\circ}C$		P _D	2.23	W
Junction temperature	Tj	150	°C	
Range of storage temperature	T _{stg}	-55 to +150	°C	

●Thermal resistance

Parameter	Symbol	Values			Unit
raiametei	Symbol	Min.	Тур.	Max.	Offic
Thermal resistance, junction - case	R_{thJC}	-	-	1.49	°C/W
Thermal resistance, junction - ambient	R_{thJA}	-	-	56	°C/W
Soldering temperature, wavesoldering for 10s	T_{sold}	-	-	265	°C

●Electrical characteristics (T_a = 25°C)

Parameter	Symbol	Conditions	Values			Unit
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Offic
Drain - Source breakdown voltage	$V_{(BR)DSS}$	$V_{GS} = 0V$, $I_D = 1mA$	200	-	-	V
		$V_{DS} = 200V, V_{GS} = 0V$ $T_{i} = 25^{\circ}C$	-	-	25	
Zero gate voltage drain current	I _{DSS}	$V_{DS} = 200V, V_{GS} = 0V$ $T_{j} = 125^{\circ}C$	-	-	100	μА
Gate - Source leakage current	I _{GSS}	$V_{GS} = \pm 30V, V_{DS} = 0V$	-	-	±100	nA
Gate threshold voltage	V _{GS (th)}	$V_{DS} = 10V$, $I_D = 1mA$	3.0	-	5.0	V
		$V_{GS} = 10V, I_D = 35A$	-	30.5	42.7	
Static drain - source on - state resistance	R _{DS(on)} *4	$V_{GS} = 10V, I_{D} = 35A$ $T_{j} = 125^{\circ}C$	-	62.0	87.0	mΩ
Forward transfer admittance	g fs	$V_{DS} = 10V, I_{D} = 35A$	15.3	30.6	-	S

●Electrical characteristics (T_a = 25°C)

Parameter	Symbol	Conditions	Values			Unit
raiametei	Symbol	Conditions	Min.	Тур.	Max.	Offic
Input capacitance	C _{iss}	$V_{GS} = 0V$	-	6900	1	
Output capacitance	C _{oss}	V _{DS} = 25V	-	400	1	pF
Reverse transfer capacitance	C _{rss}	f = 1MHz	-	230	1	
Turn - on delay time	t _{d(on)} *4	$V_{DD} \simeq 100 V$, $V_{GS} = 10 V$	-	70	1	
Rise time	t _r *4	$I_D = 35A$	-	340	-	nc
Turn - off delay time	t _{d(off)} *4	$R_L = 2.8\Omega$	-	160	-	ns
Fall time	t _f *4	$R_G = 10\Omega$	-	160	-	

● Gate Charge characteristics (T_a = 25°C)

Parameter	Symbol	Conditions	Values			Unit
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Offic
Total gate charge	Q_g^{*4}	V _{DD} ≃ 100V	-	125	-	
Gate - Source charge	Q _{gs} *4	I _D = 70A	-	40	-	nC
Gate - Drain charge	Q _{gd} *4	V _{GS} = 10V	-	50	1	
Gate plateau voltage	V _(plateau)	$V_{DD} \approx 100V, I_D = 70A$	-	7.0	-	V

●Body diode electrical characteristics (Source-Drain)(T_a = 25°C)

Parameter	Cymbol	Conditions	Values			Unit
Farameter	Symbol Conditions		Min.	Тур.	Max.	Offic
Continuous source current	I _S *1	T _c = 25°C	-	ı	70	Α
Pulsed source current	I _{SM} *2	1 _c = 23 0	-	-	140	Α
Forward voltage	V _{SD} *4	$V_{GS} = 0V, I_{S} = 70A$	-	-	1.5	V
Reverse recovery time	t _{rr} *4	I _S = 35A	-	130	-	ns
Reverse recovery charge	Q _{rr} *4	di/dt = 100A/μs	-	565	-	nC

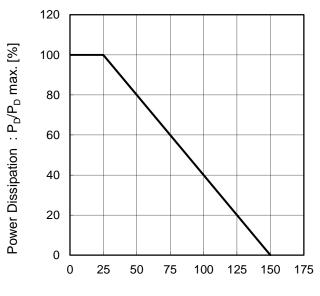
^{*1} Limited only by maximum temperature allowed.

^{*2} Pw \leq 10 μ s, Duty cycle \leq 1%

^{*3} L \simeq 500 μ H, V_{DD} = 50V, Rg = 25 Ω , starting T_j = 25°C

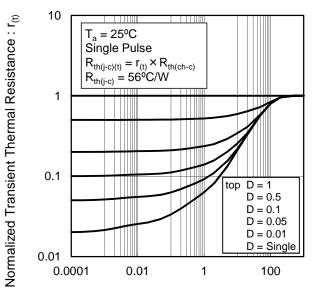
^{*4} Pulsed

Fig.1 Power Dissipation Derating Curve



Junction Temperature : T_i [°C]

Fig.2 Normalized Transient Thermal Resistance vs. Pulse Width



Pulse Width : P_W [s]

Fig.3 Avalanche Current vs Inductive Load

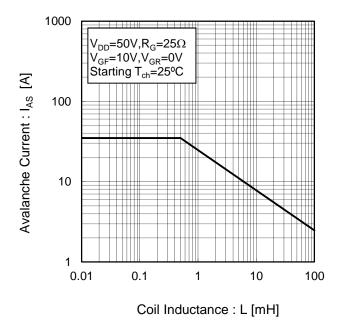
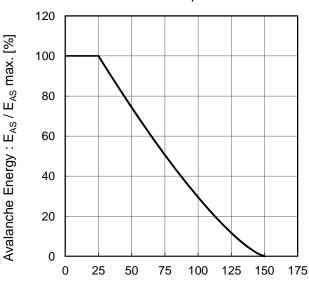
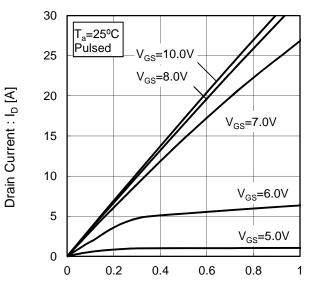


Fig.4 Avalanche Energy Derating Curve vs Junction Temperature



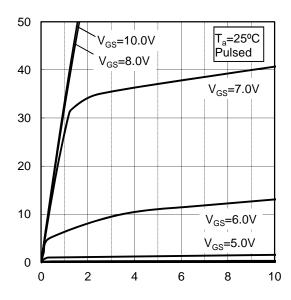
Junction Temperature : T_i [°C]

Fig.5 Typical Output Characteristics(I)



Drain - Source Voltage : V_{DS} [V]

Fig.6 Typical Output Characteristics(II)



Drain - Source Voltage : V_{DS} [V]

Drain Current : I_D [A]

Fig.7 Breakdown Voltage vs. Junction Temperature 280 Normarize Drain - Source Breakdown Voltage $V_{GS} = 0V$ 270 $I_D = 1 \text{mA}$ 260 250 240 230 220 210 200 190 180 -50 0 50 100 150 Junction Temperature : T_i [°C]

100 V_{DS}= 10V 10 Drain Current: I_D [A] 0.1 T_a= 125°C $T_a = 75^{\circ}C$ $T_a = 25^{\circ}C$ 0.01 $T_a = -25^{\circ}C$ 0.001 0 2 3 4 5 6 8 9 10

Gate - Source Voltage : V_{GS} [V]

Fig.10 Transconductance vs. Drain Current

Fig.8 Typical Transfer Characteristics

Fig.9 Gate Threshold Voltage vs. Junction Temperature 5.0 $V_{DS} = 10V$ $I_D = 1mA$ Gate Threshold Voltage: VGS(th) [V] 4.5 4.0 3.5 3.0 2.5 2.0 50 100 125 150 -50 -25 0 25 75 Junction Temperature : T_i [°C]

Static Drain - Source On-State Resistance

20

0 0

• Electrical characteristic curves

Resistance vs. Gate Source Voltage 100 Static Drain - Source On-State Resistance T_a=25°C 80 $I_D = 35A$ 60 $:R_{DS(on)}\left[m\Omega \right]$ $I_D = 50A$ 40

Fig.11 Static Drain - Source On - State

Gate - Source Voltage : V_{GS} [V]

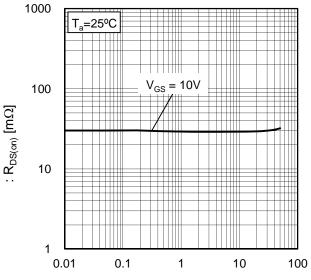
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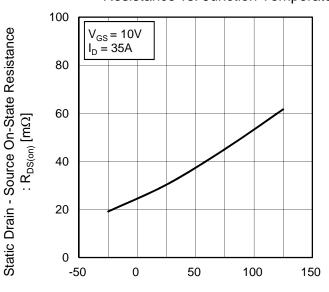
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Fig.12 Static Drain - Source On - State Resistance vs. Drain Current(I)



Drain Current : I_D [A]

Fig.13 Static Drain - Source On - State Resistance vs. Junction Temperature



Junction Temperature : T_j [°C]

Fig.14 Static Drain - Source On - State Resistance vs. Drain Current(I)

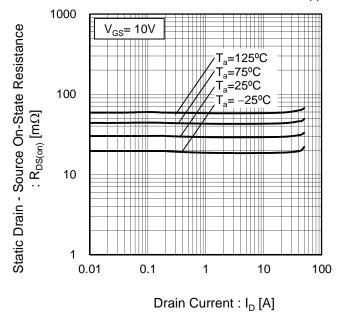
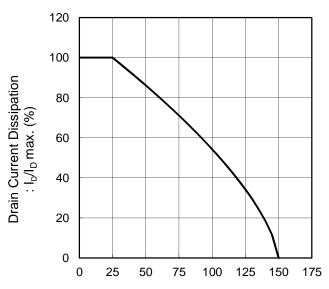
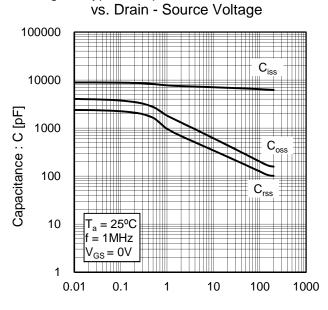


Fig.15 Drain Current Derating Curve



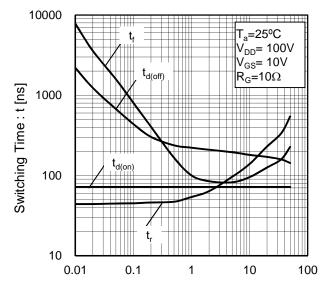
Junction Temperature : T_i [°C]

Fig.16 Typical Capacitance



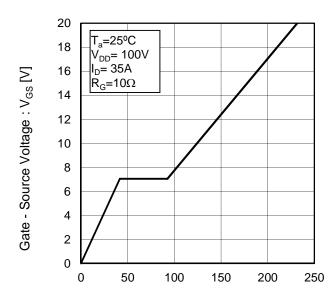
Drain - Source Voltage : V_{DS} [V]

Fig.17 Switching Characteristics

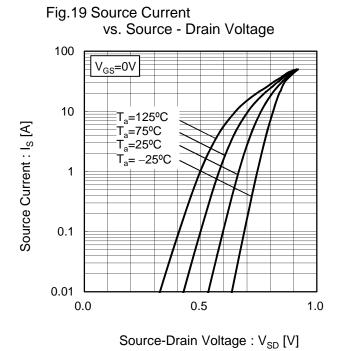


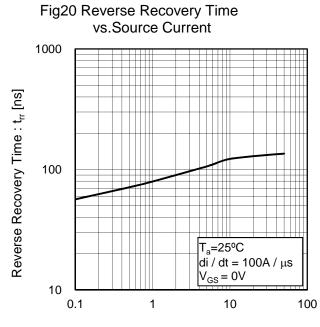
Drain Current : I_D [A]

Fig.18 Dynamic Input Characteristics



Total Gate Charge : Q_g [nC]





Source Current : I_S [A]

●Measurement circuits

Fig.1-1 Switching Time Measurement Circuit

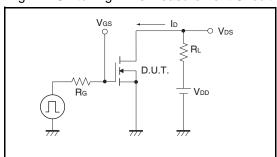


Fig.2-1 Gate Charge Measurement Circuit

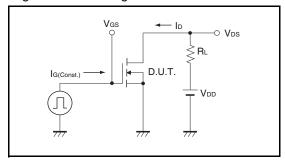


Fig.3-1 Avalanche Measurement Circuit

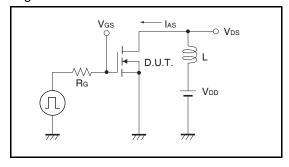


Fig.1-2 Switching Waveforms

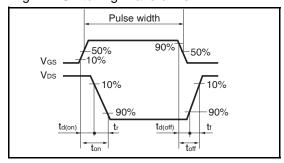


Fig.2-2 Gate Charge Waveform

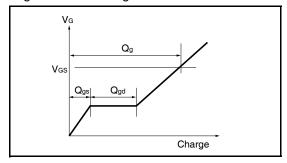
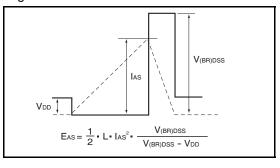
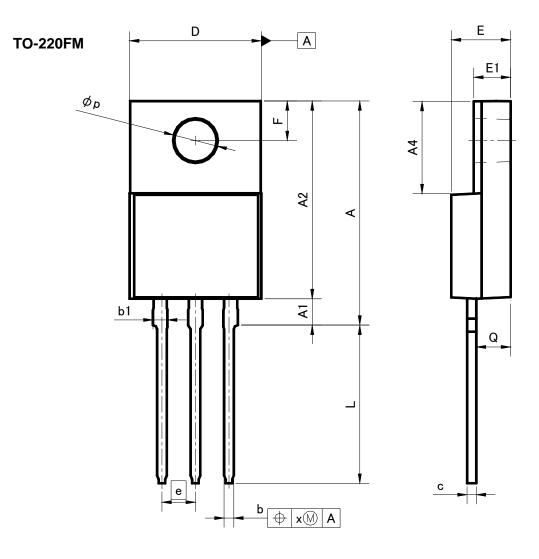


Fig.3-2 Avalanche Waveform



●Dimensions (Unit : mm)



DIM	MILIM	ETERS	INC	HES
DIM	MIN	MAX	MIN	MAX
Α	16.60	17.60	0.654	0.693
A1	1.80	2.20	0.071	0.087
A2	14.80	15.40	0.583	0.606
A4	6.80	7.20	0.268	0.283
b	0.70	0.85	0.028	0.033
b1	1.10	1.50	0.043	0.059
С	0.70	0.85	0.028	0.033
D	9.90	10.30	0.390	0.406
Е	4.40	4.80	0.173	0.189
е	2.	54	0.1	00
E1	2.70	3.00	0.106	0.118
F	2.80	3.20	0.110	0.126
L	11.50	12.50	0.453	0.492
р	3.00	3.40	0.118	0.134
Q	2.10	3.10	0.083	0.122
Х	_	0.38	_	0.015

Dimension in mm / inches

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JÁPAN	USA	EU	CHINA
CLASSⅢ	СГУССШ	CLASS II b	CL ACCIII
CLASSIV	CLASSⅢ	CLASSⅢ	CLASSⅢ

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 - [d] Use of our Products in places where the Products are exposed to static electricity or electromagnetic waves
 - [e] Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
 - [f] Sealing or coating our Products with resin or other coating materials
 - [g] Use of our Products without cleaning residue of flux (Exclude cases where no-clean type fluxes is used. However, recommend sufficiently about the residue.); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
 - [h] Use of the Products in places subject to dew condensation
- 4. The Products are not subject to radiation-proof design.
- 5. Please verify and confirm characteristics of the final or mounted products in using the Products.
- 6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse, is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- 7. De-rate Power Dissipation depending on ambient temperature. When used in sealed area, confirm that it is the use in the range that does not exceed the maximum junction temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
- ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

Precaution for Mounting / Circuit board design

- 1. When a highly active halogenous (chlorine, bromine, etc.) flux is used, the residue of flux may negatively affect product performance and reliability.
- 2. In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

For details, please refer to ROHM Mounting specification

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Precaution for Electrostatic

This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of lonizer, friction prevention and temperature / humidity control).

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- 1. Product performance and soldered connections may deteriorate if the Products are stored in the places where:
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 - [b] the temperature or humidity exceeds those recommended by ROHM
 - [c] the Products are exposed to direct sunshine or condensation
 - [d] the Products are exposed to high Electrostatic
- Even under ROHM recommended storage condition, solderability of products out of recommended storage time period
 may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is
 exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
- 4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

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